No.	PART	LOCATION	Q'TY	Maker/Vendor
1	TOP CASE ASS'Y			
2	LCD module, T240320-B3		1	SYT
3	CONN CAP, HR30-7R-C(71)		1	Hirose
4	Camera Connector Ass'y(12P)			
5	CONN, HR30-8R-12SD(71)		1	Hirose
6	Cable, CAM15P-FPCB		1	써키트라인
33	B/D Ass'y			
34	B/D ASS'Y, KAISHOT_KEYPAD B/D			
35	CONN, PH14-02P, Pinheader 1x2 1.27mm pitch, molding hegit	J102, J103	2	
36	CHIP/bead, AVL5M02200_1005	RV101, RV102, RV103	3	Armotec
37	Chip/LED, LTST-C191KRKT, RED	D101,D103	2	LITEON
38	Chip/LED, LTST-C191KGKT, GREEN	D105	1 1	LITEON
3	Chip/LED, LTST-C193TBKT-AC, BLUE	D102 R101.R102.R103	3	LITEON SAMSUNG
40	Chip/RES, CR1005 103J 10Kohm Chip/RES, CR1005 561J 560ohm	R104,R105,R106,R107	4	SAMSUNG
41	CONN. Human B2B0.5 Socket. HS05125020	J101	1	휴먼전자
43	SWITCH, KLT-1142-SMT, Tack switch	SW101, SW102, SW103	3	투인전자 팀전자
44	IC, NTS4001T16_SC70	Q101,Q102	2	Onsemi
45	PCB, mPVR_main, FR-4, 1.2T, 2Layer	101,0102	1	OHSCIIII
46	B/D Ass'v, Kaishot Main B/D			
47	BATTERY, MS621F-FL11E	BT1	1	SII
48	Speaker, MS-1368C1		1	MIC
49	Chip/Poly SW, MiniSMDC260F	F100	1	Tyco
50	Chip/bead, AVL5M02200_1005	RV1~RV5,RV9~RV15, RV800~RV806,RV809	20	Armotec
51	Chip/bead, HH-1M1608-121	FB9,FB10	2	Ceratech
52	Chip/bead, HH-1M2012-121	FB2,FB3,FB4	3	Ceratech
53	Chip/bead, MEA2010L50R0	LA1~LA6	6	TDK/기가테크
54	Chip/bead, MZA2010Y121C	FB5	1	TDK/기가테크
55	Chip/CAP, CC1005(0402) COG 101J(5%) 100pF/50V	C63,C64,C82,C83	4	SAMSUNG
56	Chip/CAP, CC1005(0402) COG 120J(5%) 12pF/50V	C29,C30	2	SAMSUNG
57	Chip/CAP, CC1005(0402) COG 150J(5%) 15pF/50V	C36,C37	2	SAMSUNG
58	Chip/CAP, CC1005(0402) COG 180J(5%) 18pF/50V	C11,C19	2	SAMSUNG
59	Chip/CAP, CC1005(0402) COG(X7R) 151K(10%) 150pF/50V	C107	1	SAMSUNG
60	Chip/CAP, CC1005(0402) COG 220J(5%) 22pF/50V	C73, C75, C84, C153	4	SAMSUNG
61	Chip/CAP, CC1005(0402) COG(X7R) 391K(10%) 390pF/50V			SAMSUNG
1	Chip/CAP, CC1005(0402) COG(X7R) 561K(10%) 560pF/50V			SAMSUNG
63	Chip/CAP, CC1005(0402) COG(X7R) 681K(10%) 680pF/50V	C28	1	SAMSUNG
64	Chip/CAP, CC1005(0402) X7R 103K(10%) 10nF/25V	DC1~DC26, C25, C96, DC73, DC75, DC77, DC79	32	SAMSUNG



No.	PART	LOCATION	Q'TY	Maker/Vendor
65	Chip/CAP, CC1005(0402) X7R 104K(10%) 100nF/10V(16V)	C4, C5, C9, C26, DC27~72, DC74, DC76, DC78, C31, C35, C44, C50, DC84~DC91, C86, C152, C124, C125, C170, C171, C172, C173, C129, C130, C131, C151, C	85	SAMSUNG
66	Chip/CAP, CC1005(0402) X7R 222K(10%) 2.2nF/50V	C13	1	SAMSUNG
67	Chip/CAP, CC1005(0402) X7R 272K(10%) 2.7nF/50V	C27	1	SAMSUNG
68	Chip/CAP, CC1005(0402) X7R(Y5V) 473K(10%) 47nF/10V	C47	1	SAMSUNG
69	Chip/CAP, CC1005(0402) Y5V 105Z(+80,-20%) 1uF/6.3V	BC1~BC27,BC29,BC31,BC33,C21, C32~C34,C43,C48,C200,C202,C126,C127,C128	41	SAMSUNG
70	Chip/CAP, CC1005(0402) Y5V 224Z(+80,-20%) 220nF/10V	C92, C93, C94	3	SAMSUNG
71	Chip/CAP, CC1608(0603) Y5V 105Z(+80,-20%) 1uF/10V	C91	1	SAMSUNG
72	Chip/CAP, CC1608(0603) Y5V 225Z(+80,-20%) 2.2uF/6.3V	C8,C45	2	SAMSUNG
73	Chip/CAP, CC1608(0603) Y5V 475Z(+80,-20%) 4.7uF/6.3V	C2,C3,C6,BC30,BC32,C42, C52,C53,C61,C62,C68,C70,C95,C97,C104,C201, C10,C18,C203,C101,C69,C802	22	SAMSUNG
74	Chip/CAP, CC2012(0805) Y5V 106Z(+80,-20%) 10uF/6.3V	C54, C55, C65, C66, C67, C12, C20,	7	SAMSUNG
75	Chip/CAP, CC2012(0805) Y5V 226Z(+80,-20%) 22uF/6.3V	C1,C7,C14~C17,C23,C24,BC28,C81,C102	11	SAMSUNG
76	Chip/CAP, CC3225(0805) Y5V 106Z(+80,-20%) 10uF/25V	C22	1	SAMSUNG
77	Chip/CAP, TT_A 22uF/6.3V, K급(10%) or M급(20%)	C41,C49	2	SAMSUNG
78	Chip/CAP, TT_C 22uF/25V, K급(10%) or M급(20%)	C39	1	SAMSUNG
79	Chip/DIODE, BAV70LT1G_SOT23	D3,D4,D6	3	Onsemi
80	Chip/DIODE, SMAB36_SMA	D1,D2	2	KEC
81	Chip/DIODE, SMFB23L_SMF	D5,D100	2	KEC
82	Chip/INDUCTOR, 1.8uH_1608	L5	1	CERATECH
83	Chip/INDUCTOR, PLF5020T-100M1R4,10uH	L4	1	TDK/기가테크
84	Chip/INDUCTOR, VLCF5020T-1R8N, 1.8uH	L100	1	TDK/기가테크
85	Chip/INDUCTOR, PLF5020T-3R3M2R6, 3.3uH	L2	1	TDK/기가테크
86	Chip/INDUCTOR, VLCF4020T-2R2N1R7, 2.2uH	L1,L3	2	TDK/기가테크
87	Chip/RES, ARRAY 4.7Kx4_2010 J급(5%)	RN4	1	SAMSUNG
88	Chip/RES, CR1005(0402) OROJ(5%) Oohm	R65,R121,R803,R804,R905,R908,R112,R911,R163,R901,J6,R802	12	SAMSUNG
89	Chip/RES, CR1005(0402) 100J(5%) 10ohm	R41,R42	2	SAMSUNG
90	Chip/RES, CR1005(0402) 101J(5%) 100ohm	R39,R43,R155,R156,R157	5	SAMSUNG
91	Chip/RES, CR1005(0402) 102J(5%) 1Kohm	R2,R25,R60,R70,R202,R205	6	SAMSUNG
92	Chip/RES, CR1005(0402) 103J(5%) 10Kohm	R7,R9,R10,R13,R14,R20,R24,R30,R31,R33~R38,R46,R55,R56,R57,R69,R73~R83,R86,R87,R92,R96,R200R201,R203,R204 R805~R809,R158,R162,R912,R61,R404,R405,R810,R811	52	SAMSUNG
93	Chip/RES, CR1005(0402) 123F(1%) 12Kohm / 1%	R103	1	SAMSUNG
94	Chip/RES, CR1005(0402) 104J(5%) 100Kohm	R51	1	SAMSUNG
95	Chip/RES, CR1005(0402) 123J(5%) 12Kohm	R94	1	SAMSUNG
96	Chip/RES, CR1005(0402) 153J(5%) 15Kohm	R8,R95,R402,R403	4	SAMSUNG
97	Chip/RES, CR1005(0402) 154J(5%) 150Kohm	R52	1	SAMSUNG
98	Chip/RES. CR1005(0402) 1653F(1%) 165Kohm / 1%	R84	1	SAMSUNG
99	Chip/RES, CR1005(0402) 1873F(1%) 187Kohm / 1%	R16	1	SAMSUNG

No.	PART	LOCATION	Q'TY	Maker/Vendor
100	Chip/RES, CR1005(0402) 220J(5%) 22 ohm	R400,R401,R64	3	SAMSUNG
	Chip/RES, CR1005(0402) 202J(5%) 2Kohm	R22	1	SAMSUNG
	Chip/RES, CR1005(0402) 2213F(1%) 221Kohm / 1%	R15,R17,R18	3	SAMSUNG
	Chip/RES, CR1005(0402) 222J(5%) 2.2Kohm	R28,R29,R53	3	SAMSUNG
	Chip/RES, CR1005(0402) 272J(5%) 2.7Kohm	R6	1	SAMSUNG
	Chip/RES, CR1005(0402) 29R43F(1%) 29.4Kohm / 1%	R102	1	SAMSUNG
	Chip/RES, CR1005(0402) 3093F(1%) 309Kohm / 1%	R23	1	SAMSUNG
107	Chip/RES, CR1005(0402) 330J(5%) 33ohm	R27,R47,R48,R90	4	SAMSUNG
108	Chip/RES, CR1005(0402) 3742F(1%) 37.4ohm / 1%	R44,R45	2	SAMSUNG
109	Chip/RES, CR1005(0402) 471J(5%) 470ohm	R32,R49,R71,R72	4	SAMSUNG
110	Chip/RES, CR1005(0402) 472J(5%) 4.7Kohm	R26	1	SAMSUNG
111	Chip/RES, CR1005(0402) 473J(5%) 47Kohm	R5,R12,R40,R909	4	SAMSUNG
	Chip/RES, CR1005(0402) 474J(5%) 470Kohm	R11,R85	2	SAMSUNG
	Chip/RES, CR1005(0402) 511J(5%) 510ohm	R1	1	SAMSUNG
	Chip/RES, CR1005(0402) 703J(5%) 70Kohm(69.8k)	R4	1	SAMSUNG
	Chip/RES, CR1005(0402) 750J(5%) 750hm	R68	1	SAMSUNG
	Chip/RES, CR1005(0402) 753J(5%) 75Kohm	R89,R91	2	SAMSUNG
	Chip/RES, CR1005(0402) 9093F(1%) 909Kohm / 1%	R21	1	SAMSUNG
	Chip/RES, CR1608(0402) 0R1F(1%) 0.1ohm / 1% Chip/RES, CR3216(0402) 0R02(1%)F 0.02ohm / 1%	R19 R3	1	VIKING VIKING
	Chip/RES, CR3216(0402) 0R02(1%)F 0.020nm / 1%	RN3	1	SAMSUNG
121	Chip/RES, ARRAY 33x4_2010 J급(5%)	RN1, RN2, RN5	3	SAMSUNG
122	CONN, 24-8005-002-100-867, SPEAKER Conncetor	J11	1	Kyocera ELCO
123	CONN, 100053FB010SX00ZL-C, T-flash Card slot	J9	1	SUYIN
124	CONN. 2x5 1.27mm Pin Header Female. Debug Port	14	1	COTTI
	CONN, DC-055, DC Jack	CN1	1	
126	CONN, PoGo pin(3P) C1.5-10.5R-3P-2.54PH-P, Battery	J1, JA1	2	MS-TECH
127	CONN, Human_B2B0.5_Plug, HP053000200 Key Connector	J8	1	휴먼전자
128	CONN, KPJ3540-05-SMT, 3.5phonejack	J7	1	
129	CONN, KUSMO4, USB mini	J2	1	
130	CONN, M04-6296-045-230-846+, LCD	J12	1	Kyocera ELCO
131	CONN, 05005HS-15F	J801	1	연호
	CONN, 2x2 1.27mm Pitch Pin Header Female(높이 3.5mm)			
	IC, CS4344CZZ_TSS0P10	U23	1	Cirrus Logic
134	IC, CS5343CZZ_TSS0P10	U21	1	Cirrus Logic
135	IC, DS2782E+T&R_TSS0P8	U3	1	Dalas
-	IC, K4M513233C_FBGA90	U11	1	삼성
-	IC, K4M561633G_FBGA54	U14	1	삼성
-	IC, K9F5608U0B_TS0P48	U12	1	삼성
139	IC, LT1618EMS_MS0P10	<u> </u> U7	1	Linear



No.	PART	LOCATION	Q'TY	Maker/Vendor
140	IC, LT1935_TS0T23	U100	1	Linear
141	IC, LX2202CLQ_MLPQ20	U2	1	Microsemi
142	IC, MAX1556ETB+T_TDFN10	U5	1	MAXIM/아메릭스
143	IC, MAX4866LEUT+T_S0T23-6	U1	1	MAXIM/아메릭스
144	IC, MAX4903ETA+T_TDFN8	U20	1	MAXIM/아메릭스
145	IC, MAX9814ETD+T_TDFN14	<u> U19</u>	1	MAXIM/아메릭스
146	IC, MG1264-169TFBGA	U13	1	Mobiligen
147	IC, MK2703SILF_SOP8	U17	1	IDT
148	IC, NCP1521BSNT1G_TS0P5	U4,U6	2	Onsemi
149	IC, NCP2820MUTBG_UDFN8	U26	1	Onsemi
150	IC, NCP5604AMTR2G_WQDN16	U27	1	Onsemi
151	IC, NTGD1100LT1G_S0T26	Q4, Q200, Q201	3	Onsemi
152	IC, NTS4001T16_SC70 IC, NUF2221W1T2G S0T363	Q3 U24	1	Onsemi
153				Onsemi 삼성
154	IC, S3C2440A-40_FBGA289	U8	1	
155	IC, ADV7179BCPZ_LFCSP	U22	1	Analog Device
156	IC, WM9715LGFL/RV_48LEAD_QFN	U25	1	Wolfson
157	IC, TVP5150AM1PBS_TQFP32	U16	1	TI/AVNET
158	IC, XC61FN2712M_S0T23	U10	1	Torex
159	IC, XC6209F-132MR_S0T25	U9	1	Torex
160	IC, XC6209F-182MR_S0T25	U15	1	Torex
161	IC, XC6209F-332MR_S0T25	U18, U35	2	Torex
	SWITCH, ID-1120BS, Detect	SW2	1	팀전자
	SWITCH, KLT-1107U-N	SW1,SW3,SW4	3	팀전자
	SWITCH, KLT-1146C-A2-SMT	SW5	1	팀전자
	TR/FET, IRLML2502TR_S0T23	Q9	1	I OR
	TR/FET, IRLML6401TR_S0T23	Q8	1	I OR
	TR/NPN, BC846BDW_S0T363	Q7	1	Onsemi
	TR/NPN, MMBT3906_S0T23	Q2	1	Onsemi
	XTAL, 0SC 12Mhz_SC0-32, 3.3V,3.2x2.5 mm	0801	1	ELTRON ELTRON
	XTAL, 14.31818Mhz_SX-32, 18pF, 3.2x2.5mm	Y2 X1	1	ELTRON ELTRON
Van	XTAL, 24.576Mhz_SX-32, 18pF, 3.2x2.5mm XTAL, 32.768Khz, SSP-T7-F	X Y1	1	ELTRON
Sec	EMI Filter, LZA10-2ADC474M 1608	EF100.EF101.EF150~EF153.EF801	7	
	Chip/RES, CR1005(0402) 151J(5%) 150 ohm	R150	1	Mitsubishi SAMSUNG
	Chip/CAP, TT_B 47uF/10V, K급(10%) or M급(20%)	C103.C108	2	SAMSUNG
-	Chip/CAP, TT_A 10uF/16V, K급(10%) or M급(20%)	C121,C122,C123,C806	4	SAMSUNG
	Chip/CAP, TT A 2.2uF/16V, K급(10%) or M급(20%)	C120.C132.C133	3	SAMSUNG
	Chip/CAP, CC1005(0402) X7R 271K(10%) 270pF/50V	C59	1	SAMSUNG
	EMI Filter, LFB20-3D1E471M	FB1,FB6,FB7,FB8,FB11,FB201,FB800,EF800	8	Mitsubishi



No.	PART	LOCATION	Q'TY	Maker/Vendor
180	Chip/RES. CR1608(0603) OROJ(5%) 0 ohm	R93.R131.R170	3	SAMSUNG
181	Chip/RES, CR1005(0402) 122J(5%) 1.2k ohm	R154	1	SAMSUNG
182	Chip/CAP, CC1005(0402) COG(X7R) 331K(10%) 330pF/50V	C60,C800, C801	3	SAMSUNG
183	Chip Voltage Refernce, AD1580ART_REEL, S0T23	D150	1	Analog Device
}	CONN. 05005HS-10F	J800	1	연호전자
	PCB, mPVR_main, FR-4, 1.2T, 10Layer		1	
186				
187	모듈 별 옵션 setting 값			
188	12P hybrid(Camera+USB+GPS) only			
189	Chip/RES, CR1005(0402) OROJ(5%) O ohm	R406,R407	2	SAMSUNG
190	Chip/RES, CR1608(0603) 0R0J(5%) 0 ohm	R420	1	SAMSUNG
\$ ************************************	EMI Filter, LZA10-2ADC474M_1608	EF802,EF803	2	Mitsubishi
192				
	12P hybrid(Camera+GPS) + 6P(USB)			
-	Chip/RES, CR1005(0402) 0R0J(5%) 0 ohm	R418,R419	2	SAMSUNG
	Chip/RES, CR1608(0603) OROJ(5%) 0 ohm	R413,R415	2	SAMSUNG
-	EMI Filter, LZA10-2ADC474M_1608	EF802,EF803	2	Mitsubishi
197				
	Camera Connector hex Nut(HR30-6R-6SD 부속품), Optional			
	Camera Connector Lock Washer(HR30-6R-6SD 부속품), Optional			
	Camera Connector Gasket(HR30-6R-6SD 부속품), Optional			111
-	CONN CAP, HR30-6R-C(71), Optional		1	Hirose
	Connector Ass'y (06P), Optional			11.
-	CONN, HR30-6R-6SD(71), Optional		1	Hirose
204	Cable, CAMO6P-FPCB, Optional		1	써키트라인
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